

KRFULL (Korean Patents Full-Text)

File Subject Coverage	All patent-relevant areas of science and technology, i.e., all classes of the International Patent Classification			
File Type	Full-Text			
Features	Thesauri	International Patent Classification (/IPC), Cooperative Patent Classification (/CPC)		
	Alerts (SDIs)	Weekly or monthly (weekly is the default)		
	CAS Registry Number® Identifiers	☐	SLART	☒ Structures ☐
	Keep & Share	☒	Register Links	☒
Record Content	• Full-text of patent applications, granted patents, and utilities models published by the Korean Intellectual Property Office in the Republic of Korea from 1978 onwards. • New records are available about six days after publication date with the complete content. • Records are available about six days after publication date with the complete content • Records contain bibliographic data including patent applicant and inventor, patent, application, priority, and related application data, IPC and CPC classification codes, abstract, and full-text of description and claims. • Abstracts, detailed descriptions and claims are machine translated to English; the titles human translated. • Title, abstract, detailed description, and claims as well as patent assignees, inventors and agents are displayable in Korean characters. • Standardized and normalized patent assignee names are searchable in their own fields /PAS and /PAN. • Numeric values of 59 physical and chemical properties are searchable in about 20,000 variants of the base and additional units within all full text fields in English. • Ultimate Owners are searchable in the field /UO and /UOS • Key terms, indexed and displayed in the field /KT, enhance retrieval of relevant results, and make the evaluation of results more efficient. They are useful to broaden search scope more precisely than Basic Index searches. • Database records comprise all documents published for one application. • Some of the full-text has been created by Optical Character Recognition (OCR) software. Therefore, a small number of characters may have been misinterpreted, or portions of the text may have been incompletely recognized.			
File Size	• More than 5.7 million family records with more than 8.2 million publications (01/2026) • More than 5 million front page images from 1978 to present (01/2026)			
Coverage	1978 - present			
Updates	Weekly			
Language	English, Korean			

Database Producer	LexisNexis Business Information Solutions B.V. Radarweg 29 1043 NX Amsterdam The Netherlands Copyright Holder
Sources	Patent applications, granted patents, and utilities models published by the Korean Intellectual Property Office
User Aids	• Online Helps (HELP DIRECTORY lists all help messages available) • STNGUIDE
Clusters	• AEROTECH • ALLBIB • AUTHORS • CORPSOURCE • ENGINEERING • FULLTEXT • HPATENTS • NPS • PATENTS • PNTTEXT STN Database Cluster information

Search and Display Field Codes

If multiple search terms are linked with and AND-operator, all terms are searched in the complete database record, i.e., in all publications referring to one application. For a search in a specific publication of the record, connect the search term and the patent kind code with the (L)-proximity operator, e.g., S BOREHOLE/AB, TI, CLM (L) KRA/PK limits the search to Japanese applications KRA.

Fields that allow left truncation are indicated by an asterisk (*).

General Search Fields

Search Field Name	Search Code	Search Examples	Display Codes
Basic Index* (contains single words from title (TIEN), abstract (AB), detailed description (DETD), claims (CLM), main claims (MCLM) fields), and keyterms (KT)	None or /BI	S TRANSISTOR AND ELECTRODE S ACOUSTIC SENSOR S ?TRANSFER?	TIEN, AB, ABEN, DETD, DETDEN, CLM, CLMEN, MCLM, MCLMEN, KT
Abstract*	/AB	S BOREHOLE/AB	AB
Abstract (English)*	/ABEN	S BOREHOLE/ABEN	AB, ABEN
Accession Number	/AN	S 599999/AN	AN
Application Country (WIPO code and text)	/AC	S KR/AC	AI
Application Date (1)	/AD	S AD=JAN 2011	AI
Application Kind Code	/AK	S KRA/AK	AI
Application Number (2)	/AP	S KR2012-100038/AP	AI
Application Number Original	/APO	S KR2019760001984/APO	AI
Application Year (1)	/AY	S AY>=2005	AI
Claims*	/CLM	S DERIVATION/CLM	CLM
Claims (English)*	/CLMEN	S DERIVATION/CLMEN	CLM, CLMEN
Claims, Claim Groups*	/CLM.CG	S OFFICE CHAIR/CLM.CG	CLM, CLM.CG
Claims, Independent Claims*	/CLM.IC	S OFFICE CHAIR/CLM.IC	CLM.IC, CLM, CLMEN
Cooperative Patent Classification (3)	/CPC	S C12N0009/CPC	CPC
Cooperative Patent Classification, Action Date	/CPC.ACD	S 20121113/CPC.ACD	CPC.TAB
Cooperative Patent Classification, Keyword	/CPC.KW	S C12N0009/CPC (S) I/CPC.KW	CPC.TAB
Cooperative Patent Classification, Version	/CPC.VER	S 20130101/CPC.VER	CPC.TAB
CPC, Combination Set	/CPC.CS	S C08L0079-02/CPC.CS	CPC
Data Entry Date (1)	/DED	S 20190930-20191031/DED	DED
Data Update Date (1)	/DUPD	S 20190828/DUPD	DUPD
Detailed Description	/DETD	S *LASER/DETD	DETD, DETDEN
Detailed Description (English)	/DETDEN	S LASER LIGHT/DETDEN	DETDEN, DETD
Document Type (code and text)	/DT (or /TC)	S PATENT/DT	DT
Entry Date (1)	/ED	S ED=DEC 2019	ED
Entry Date of Full-Text (1)	/EDTX	S EDTX>20191130	EDTX
Field Availability	/FA	S ABENFA	FA
International Patent Classification (ICM, ICS, IPCI, IPCR) (3)	/IPC	S A01B0001-16/IPC	ICM, ICS, IPCI, IPCR
Inventor	/IN (or /AU)	PARK A REUM/IN	IN
Inventor, Country (WIPO code and text)	/IN.CNY	S KR/IN.CNY	IN, IN.CNY
Inventor, Total	/IN.T	S MILLER ALFRED/IN.T	IN
IPC Initial	/IPCI	S B21B0001/IPCI	IPCI, IPC
IPC, Keyword Terms	/IPC.KW	S INITIAL/IPC.KW	IPC.TAB
IPC Main	/ICM (or /IPCM)	S B29B001-06/ICM	ICM, IC

General Search Fields (cont'd)

Search Field Name	Search Code	Search Examples	Display Codes
IPC, Reclassified	/IPCR	S B21D0007-08/IPCR	IPCR, IPC
IPC, Reform	/IPC.REF	S A01B0001-16/IPC.REF	IPC.TAB
IPC Secondary	/ICS (or /IPCS)	S B29H003-00/ICS	ICS, IC
IPC, Version 1-7 (ICM, ICS)	/IC	S A47J0314-00/IC	IC, ICM, ICS
IPC, Version 1-7	/IC.VER	S 7/IPC.VER	IPC.TAB
IPC, Version 1-8	/IPC.VER	S 7/IPC.VER	IPC.TAB
Key Terms*	/KT	S (LASER(3A)SOURCE?)/KT	KT
Language (code and text)	/LA	S KO/LA	LA
Language, Filing (code and text)	/LAF	S KO/LAF	LAF
Main Claim*	/MCLM	S ?LASER/MCLM	MCLM
Main Claim (English)*	/MCLMEN	S ?FRACTURE?/MCLMEN	MCLMEN, MCLM
Number of Claims (1)	/CLMN	S 5-10/CLMN	CLMN
Number of Paragraphs in DETD (Detailed Description) (1)	/DETN	S 20-30/DETN	DETN
Patent Assignee (4)	/PA (or /CS)	S SAMSUNG/PA	PA
Patent Assignee, Country	/PA.CNY	S KR/PA.CNY	PA, PA.CNY
Patent Assignee, Total	/PA.T	S SAMSUNG AEROSPACE IND. CO., LTD./PA	PA
Patent Assignee Normalized	/PAN	S SAMSUNG/PAN	PAN
Patent Assignee Standardized	/PAS	S SAMSUNG AEROSPACE INDUSTRIES/PAS	PAS
Patent Country (WIPO code and text)	/PC	S KR/PC	PI
Patent Information Type	/PIT	S KRA OFFICIAL GAZETTE OF THE UNEXAMINED PATENTS/PIT	PIT
Patent Kind Code	/PK	S KRA1/PK	PI
Patent Number (2)	/PN	S KR210004U/PN	PI
Patent Number Original	/PNO	S KR300381757/PNO	PNO
Patent Number/Kind Code	/PNK	S KR210005 Y1/PNK	PI
Patent Status Established Date	/STED	S 20250227/STED	STED
Patent Status Indicator	/STI	S A/STI	STI
Physical Properties	/PHP	S PHV/PHP (S) BUFFER/BI	KWIC
Priority Country (WIPO code and text)	/PRC	S KR/PRC	PRN
Priority Date (1)	/PRD	S KOREA, REPUBLIC OF/PRC	
Priority Date First (1)	/PRDF	S PRD=MAY, 20 2003	PRN
Priority Number (2)	/PRN	S 20030520/PRD	PRN
Priority Number Original	/PRNO	S 20010704/PRDF	PRN
Priority Year (1)	/PRY	SAT1982-2545/PRN	PRNO, PRAO
Priority Year First (1)	/PRYF	S AT0100016/PRNO	PRN
Publication Date (1)	/PD	S 1999/PRY	PRN
Publication Year (1)	/PY	S 1999/PRYF	PI
Related Application Country	/RLC	S 19990108/PRD	PI
Related Application Number	/RLN	S 2017/PY	RLI
Related Application Date (1)	/RLD	S WO/RLC	RLI
Related Application Type	/RLT	S WO1982-JP96/RLN	RLI
Related Application Year (1)	/RLY	S 20120109/RLD	RLI
Related Patent Country	/RLPC	S PCT APPLICATION/RLT	RLI
Related Publication Date	/RLPD	S 2017/RLY	RLI
Related Patent Number (2)	/RLPN	S WO/RLPC	RLI
Related Publication Year	/RLPY	S 20210805/RLPD	RLI
Title*	/TI	S WO2000000071/RLPN	RLI
Title (English)*	/TIEN	S 2019/RLPY	RLI
		S LASER/TI	TI
		S LASER/TIEN	TI, TIEN

General Search Fields (cont'd)

Search Field Name	Search Code	Search Examples	Display Codes
Ultimate Owner (4) Ultimate Owner Standardized (4) Update Date (1) Update Date Full-Text (1)	/UO /UOS /UP /UPTX	S KIA/UO S KIA/UOS S 20191113/UP S 20191030/UPTX	UO UOS UP UPTX

(1) Numeric search field that may be searched using numeric operators or ranges.

(2) By default, patent numbers, application and priority numbers are displayed in STN Format. To display them in Derwent format, enter SET PATENT DERWENT at an arrow prompt. To reset display to STN Format, enter SET PATENT STN.

(3) An online thesaurus is available in this field.

(4) Search with implied (S) proximity is available in this field.

Super Search Fields

Enter a super search code to execute a search in one or more fields that may contain the desired information. Super search fields facilitate cross-file and multifile searching. EXPAND may not be used with super search fields. Use EXPAND with the individual field codes instead.

Search Field Name	Search Code	Fields Searched	Search Examples	Display Codes
Application Number Group	/APPS	AP, APO, PRN, PRNO, RLN	S KR2012-100038/APPS	AI, APO, PRAI, RLI, APPS
Patent Assignee Group	/PASS	PA, PA.T, PAS, PAN, UO	S SAMSUNG/PASS	PA, PAS, PAN, UO, PASS
Patent Number Group	/PATS	PN, PNO, RLPN	S KR 1399575/PATS	PN, RLPN, PNO, PATS

Property Fields ⁽¹⁾

In KRFULL a numeric search for a specific set of physical properties (/PHP) is available within the full-text fields (TI, AB, DETD, CLM, BI). The numeric values are not displayed as single fields, but highlighted within the hit displays.

Use EXPAND/PHP to search for all available physical properties. A search with the respective field codes will be carried out in all database fields with English text. The /PHP index contains a complete list of codes and related text for all physical properties available for numeric search.

Field Code	Property	Unit	Symbol	Search Examples
/AOS	Amount of substance	Mol	mol	S 10 /AOS
/BIR	Bit Rate	Bit/Second	bit/s	S 8000-10000/BIR
/BIT	Stored Information	Bit	Bit	S BIT > 3 MEGABIT
/CAP	Capacitance	Farad	F	S 1-10 MF/CAP
/CATA	Catalytic Activity	Katal	kat	S 1-10/CATA
/CDN	Current Density	Ampere/Square Meter	A/m ²	S CDN>10 A/M**2
/CMOL	Molarity, Molar Concentration	Mol/Liter	mol/L	S UREA/BI (S) 8/CMOL
/CON	Electrical Conductance	Siemens	S	S 1S-3/CON
/DB	Decibel	Decibel	dB	S DB>50
/DEG	Degree	Degree	°	S CYLINDER/BI (S) 45/DEG
/DEN (/C)	Density (Mass Concentration)	Kilogram/Cubic Meter	kg/m ³	S 5E-3-10E-3/DEN
/DEQ	Dose Equivalent, Absorbed Dose	Sievert	Sv	S 100/DEQ
/DOA	Dosage	Milligram/Kilogram/Day	mg/kg/day	S 100-300/DOA
/DOS (/LD50)	Dose	Milligram/Kilogram	mg/kg	S DOS>0.8
/DV	Viscosity, dynamic	Pascal * Second	Pa * s	S DV>5000
/ECH (/CHA)	Electric Charge, Capacity	Coulomb	C	S 0.0001-0.001/ECH
/ECO (/ECND)	Electrical Conductivity	Siemens/Meter	S/m	S ECO>800 S/M (15A) AQUEOUS
/ELC (/ECC)	Electric Current	Ampere	A	S 1-10/ELC
/ELF (/ECF)	Electric Field	Volt/Meter	V/m	S 200/ELF
/ENE	Energy	Joule	J	S DROPLETS (10A) 40 JOULE - 70 JOULE /ENE
/ERE (/ERES)	Electrical Resistivity	Ohm * Meter	Ohm * m	S ERE>0.1
/FOR	Force	Newton	N	S 50 N /FOR
/FRE (/F)	Frequency	Hertz	Hz	S OSCILLAT?/BI (S) 1- 3/FRE
/IU	International Unit	none	IU	S IU>1000 (P) VITAMIN A
/KV	Viscosity, kinematic	Square Meter/Second	m ² /s	S METHYLPOLYSILOXANES/BI (10A) 200-300 CST /KV
/LEN (/SIZ)	Length, Size	Meter	m	S 1-4/LEN
/LUME	Luminous Emittance, Illuminance	Lux	lx	S 10-50/LUME
/LUMF	Luminous Flux	Lumen	Lm	S LUMF>1000
/LUMI	Luminous Intensity	Candela	cd	S LUMI<4
/M	Mass	Kilogram	kg	S ALLOY/BI (30A) 1E-10-1E-5/M
/MCH	Mass to Charge Ratio	none	m/z	S MCH=1
/MFD (/MFS)	Magnetic Flux Density	Tesla	T	S MFD>102
/MFR (/MFL)	Mass Flow Rate	Kilogram/Second	kg/s	S MFR<0.1
/MFST	Magnetic Field Strength	Ampere/Meter	A/m	S MFST/PHP

Property Fields⁽¹⁾ (cont'd)

Field Code	Property	Unit	Symbol	Search Examples
/MM (/MW, /MOM)	Molar Mass, Molecular Weight	Gram/Mol	g/mol	S 2000-3000 G/MOL/MM
/MOLS	Molality of Substance	Mol/Kilogram	mol/kg	S 01.-10 MOL/KG/MOLS
/MVR	Melt Volume Rate, Melt Flow Rate	none	g/10 min	S 3/MVR
/PER	Percent (Proportionality)	none	%	S POLYMER?/AB (5A) 4/PER
/PHV (/PH)	pH Value	pH	pH	S 7.4-7.6/PHV
/POW (/PW)	Power	Watt	W	S "HG-XE-?"/BI (S) 100-200 WATT/POW
/PPM	Parts per million	Ppm	ppm	S 100 PPM /PPM (10A) ADDITIVE/BI
/PRES (/P)	Pressure	Pascal	Pa	S (VACUUM (5A) DISTILL?)/BI (S) 1000-1100/PRES
/RAD	Radioactivity	Becquerel	Bq	S RAD/PHP
/RES	Electrical Resistance	Ohm	Ohm	S SENSOR /BI (S) 10- 100/RES
/RI	Refractive Index	none	none	S 3-4/RI
/RSP	Rotational Speed	Revolution/Minute	rpm	S 2 RPM - 100 RPM /RSP (S) ENGINE/BI
/SAR	Area	Square Meter	m ²	S PLATE/BI (S) 10 M**2 - 100 M**2 /SAR
/SOL (/SLB)	Solubility	Gram/100 gram	g/100 g	S SOL>20 G/100G (5A) WATER
/SSAM	Specific Surface Area, Mass	Square Meter/ Kilogram	m ² /kg	S 1-10/SSAM
/STSC (/ST)	Surface Tension, Spring Constant	Joule /Square Meter	J/m ²	S 60 J/M**2/STSC
/TCO (TCND)	Thermal Conductivity	Watt/Meter * Kelvin	W/m * K	S 1/TCO (S) HEAT?
/TEMP (/T)	Temperature	Kelvin	K	S 20-25/TEMP
/TEX	Tex	Gram/Kilometer	g/km	S 1-5/TEX
/TIM	Time	Second	s	S ?/INCUB?/BI (10A) 50 S - 150 S /TIM
/VEL (/V)	Velocity	Meter per Second	m/s	S REDUC?/BI (S) 1E-3-5E-3/VEL
/VELA	Velocity, angular	Radian/Second	rad/s	S VELA>10
/VLR	Volumetric Flow Rate	Cubic Meter/Second	m ³ /s	S 1 M**3/S - 2 M**3/S /VLR (S) ABRASIVE
/VOL	Volume	Cubic Meter	m ³	S 1E-8-2E-8/VOL.EX
/VOLT	Voltage	Volt	V	S TENSION/BI (10A) 5E-3 V <VOLT<7E-3 V

1) Exponential format is recommended for the search of particularly high or low values, e.g., 1.8E+7 or 1.8E7 (for 18000000) or 9.2E-8 (for 0.000000092).

International Patent Classification (/IPC) Thesaurus

The classifications, validity and catchwords for the main headings and subheadings from the current (8th) edition of the WIPO International Patent Classification (IPC) manual are available. The classifications from the previous editions (1-7) are also available as separate thesauri. To EXPAND and SEARCH in the thesauri for editions 1–7, use the field code followed by the edition number, e.g., /IPC2, for the 2nd edition. Catchwords are included only in the thesauri for the 8th, 7th, 6th, and 5th editions.

Relationship Code	Content	Examples
ADVANCED (ADV)	Advanced Codes for the Core Level IPC Code	E A61K0006-06+ADVANCED/IPC
ALL	All Associated Terms (BT, SELF, NT, RT)	E C01C003-00+ALL/IPC
BRO (MAN)	Complete Class	E C01C+BRO/IPC
BT	Broader Term (BT, SELF)	E C01F001-00+BT/IPC
CORE (COR)	Core Codes for the Advanced Level IPC Code	E G08C0019-22+CORE/IPC
ED	Complete title of the SELF term and IPC manual edition	E C01F001-00+ED/IPC
HIE	Hierarchy Term (Broader and Narrower Term) (BT, SELF, NT)	E C01B003-00+HIE/IPC
INDEX	Complete title of the SELF term	E C01F001-00+INDEX/IPC
KT	Keyword Term (catchwords) (SELF, KT)	E CYANOGEN+KT/IPC
NEXT	Next Classification	E C01C001-00+NEXT5/IPC
NT	Narrower Terms (SELF, NT)	E C01C+NT/IPC
PREV	Previous Classification	E C01C001-12+PREV10/IPC
RT (SIB)	Related Terms (SELF, RT)	E C01C003-20+RT/IPC
TI	Complete Title of the SELF Term and Broader Terms (BT, SELF)	E C01F001-00+TI/IPC

CPC Thesaurus

This thesaurus is available in the /CPC search field. All relationship codes can be used with both the EXPAND and SEARCH commands.

Relationship Code	Content	Search Examples
ALL	All usually required terms (BT, SELF, CODE, DEF)	E C12M0001-005+ALL/CPC
AUTO (1)	Automatic relationship (BT, SELF, CODE, DEF)	E G01J003-443+AUTO/CPC
BT	Broader terms (BT, SELF)	E G01J0003-443+BT/CPC
CODE	Classification Code (SELF, CODE)	E CARTRIDGES+CODE/CPC
DEF	Definition (SELF, DEF)	E B65G0045-16+DEF/CPC
HIE	Hierarchy terms (all broader and narrower terms) (BT, SELF, DEF, NT)	E A01B0001+HIE/CPC
KT	Keyword terms (SELF, KT)	E LASER+KT/CPC
MAX	All associated terms	E G01J0003-44+MAX/CPC
NEXT	Next classification within the same class (SELF, NEXT)	E A01B0001-24+NEXT/CPC
NEXT(n)	Next n classification within the same class	E A01B0001-24+NEXT3/CPC
NT	Narrower terms	E G05B0001-04+NT/CPC
PREV	Previous Code within the same class (SELF, PREV)	E G05B0019-00+PREV/CPC
PREV(n)	Previous n classifications within the same class	E G05B0019-00+PREV2/CPC
TI	Complete Title of SELF Term and Broader Terms (BT, SELF)	E G05B0001-03+TI/CPC

(1) Automatic Relationship is SET OFF. In case of SET REL ON, the result of EXPAND or SEARCH without any relationship code is the same as described for AUTO.

DISPLAY and PRINT Formats

Any combination of formats may be used to display or print answers. Multiple codes must be separated by spaces or commas, e.g., D L1 1-5 TI PA. The fields are displayed or printed in the order requested.

The information of the latest publication is displayed by default. To display the content for all levels of the record you can combine all display fields and formats with the qualifier .M except FA, SCAN, and TRIAL.

For displaying a particular publication of a database record, you can simply add for certain display field the kind code to the appropriate display format, e.g., ALL.A. Fields that allow this are indicated by a number (3).

Hit-term highlighting is available for all fields. Highlighting must be ON during SEARCH to use the HIT, KWIC, and OCC formats.

The default display format is STD.M, i.e., all publication levels of one family in the STD format.

Format	Content	Examples
AB (ABS)	Abstract	D TI AB 1-5
ABEN	Abstract (English)	D ABEN
ABKO	Abstract (Korean)	D ABKO
AGKO (2)	Agent (Korean characters)	D AGKO
AI (AP) (1)	Application Information	D AI
AN	Accession Number	D L3 AN
CLM (3)	Claims	D CLM
CLM.CG (3)	Claims, Claim Groups	D CLM.CG
CLM.IC (3)	Claims, Independent Claims	D CLM.IC
CLMEN (3)	Claims (English)	D CLMEN
CLMKO	Claims (Korean)	D CLMKO
CLMN (2)	Number of Claims	D CLMN
CPC	Cooperative Patent Classification	D CPC
CPC.TAB	CPC, Tabular	D CPC.TAB
DETDEN (3)	Detailed Description	D DETD
DETDKO	Detailed Description (Korean)	D DETDKO
DETN (2)	Number of Paragraphs in DETD	D DETN
DT (TC)	Document Type	D DT
ED	Entry Date	D ED
EDP	Entry Date Patent	D EDP
EDTX	Entry Date of Full-Text	D EDTX
FA	Field Availability (for all publication levels)	D FA
GI	Graphic Image	D GI
IC	International Patent Classification, Version 1-7, (ICM, ICS)	D IC
ICM	IPC Main	D IC
ICS	IPC Secondary	D ICS
IN (AU)	Inventor (English)	D IN
IN.CNY	Inventor, Country	D IN.CNY
INKO	Inventor (Korean)	D INKO
IPC	International Patent Classification, Version 1-8 (ICM, ICS, IPCI, IPCR)	D IPC
IPCI	IPC Initial	D IPCI
IPCR	IPC Reclassified	D IPCR
KT	Key Terms	D KT
LA	Language	D LA
LAF	Language of Filing	D LAF
MCLM	Main Claim	D MCLM
MCLMEN	Main Claim (English)	D MCLMEN
MCLMKO	Main Claim (Korean)	D MCLMKO
PA (CS)	Patent Assignee/ (English)	D PA
PA.CNY	Patent Assignee, Country	D PA.CNY
PAKO	Patent Assignee (Korean)	D PAKO
PAN	Patent Assignee Normalized	D PAN
PAS	Patent Assignee Standardized	D PAS
PI (PN) (1)	Patent Information	D PI
PIT	Patent Information Type	D PIT
PNO	Patent Number Original	D PNO
PRN (PRAI) (1, 5)	Priority Information	D PRN
PRNO (PRAO) (2)	Priority Number Original	D PRNO
RLI (RLN)	Related Application Information	D RLI

DISPLAY and PRINT Formats (cont'd)

Format	Content	Examples
RLPI STED STI TI TIEN TIKO TIEN TIKO UO UOS UP UPTX	Related Patent Information Patent Status Established Date Patent Status Indicator Title Title (English) Title (Korean) Title (English) Title (Korean) Ultimate Owner Ultimate Owner Standardized Update Date Update Date Full-Text	D RLPI D STED D STI D TI D TIEN D TIKO D TIEN D TIKO D UO D UOS D UP D UPTX
ALL (1, 3) ALLG IALL (1, 3) IALLG DALL (1) APPS (1) BIB (1) BIBG BIBO IBIB (1) IBIBG BRIEF (1) BRIEFO IBRIEF (1) IBRIEFG IND IPC IPC.TAB CPC.TAB MAX (ALL.M) (1) MAXG (1) MAXO IMAX (IALL.M) (1) IMAXG SCAN (4) STD (1) ISTD (1) TRIAL (TRI, SAM, SAMPLE, FREE) TX TXO	AN, EDP, ED, UP, EDTX, UPTX, DED, DUPD, TIEN, TIKO, IN, PA, PAS, PAN, UO, UOS, LAF, LA, DT, PI, PIT, STI, AI, PRAI, RLI, RLPI, ICM, ICS, IPCI, IPCR, CPC, ABEN, DETDEN, CLMEN, KT ALL, plus graphic image ALL, indented with text labels IALL, plus graphic image ALL, delimited for post processing AI, RLN, PRAI AN, EDP, ED, EDTX, UP, UPTX, DED, DUPD, TIEN, TIKO, IN, PA, PAS, PAN, UO, UOS, LAF, LA, DT, PI, PIT, STI, AI, PRAI, RLI, RLPI BIB, plus graphic image AN, EDP, ED, EDTX, UP, UPTX, TIEN, TIKO, IN, INKO, PA, PAS, PAN, PAKO, UO, UOS, AGKO, LAF, LA, DT, PI, PIT, STI, AI, PRAI, RLI, RLPI BIB, indented with text labels IBIB, plus graphic image AN, EDP, ED, EDTX, UP, UPTX, DED, DUPD, TIEN, TIKO, IN, PA, PAS, PAN, UO, UOS, LAF, LA, DT, PI, PIT, STI, AI, PRAI, RLI, RLPI, ICM, ICS, IPCI, IPCR, CPC, ABEN, MCLMEN, KT AN, EDP, ED, EDTX, UP, UPTX, TIEN, TIKO, IN, INKO, PA PAS, PAN, PAKO, UO, UOS, AGKO, LAF, LA, DT, PI, PIT, STI, AI, PRAI, RLI, RLPI, ICM, ICS, IPCI, IPCR, CPC, ABEN, ABKO, MCLMEN, MCLMKO, KT BRIEF, indented with text labels IBRIEF, plus graphic image ED, IPC (ICM, ICS, IPCI, IPCR), CPC International Patent Classification (ICM, ICS, IPCI, IPCR) IPC, IPC.KW, IPC.VER, in tabular version CPC, in tabular version AN, EDP, ED, EDTX, UP, UPTX, DED, DUPD, TIEN, TIKO, IN, PA, PAS, PAN, UO, UOS, LAF, LA, DT, PI, PIT, STI, AI, PRAI, RLI, RLPI, ICM, ICS, IPCI, IPCR, CPC, ABEN, DETDEN, CLMEN, KT, FA, from all publication levels MAX, plus graphic image AN, EDP, ED, EDTX, UP, UPTX, TIEN, TIKO, IN, IN.CNY, INKO, PA, PA.CNY, PAS, PAN, PAKO, UO, UOS, AGKO, LAF, LA, DT, PI, PIT, STI, AI, PRAI, RLI, RLPI, ICM, ICS, IPCI, IPCR, CPC, ABEN, ABKO, DETDEN, DETDKO, CLMEN, CLMKO, KT, FA for all levels of publication MAX, indented with text labels IMAX, plus graphic image TI (random display without answer numbers) AN, EDP, ED, EDTX, UP, UPTX, DED, DUPD, TIEN, TIKO, IN, PA, PAS, PAN, UO, UOS, LAF, LA, DT, PI, PIT, STI, AI, PRAI, RLI, RLPI, ICM, ICS, IPCI, IPCR, CPC (STD.M is default) STD, indented with text labels EDP, ED, EDTX, UP, UPTX, TIEN, FA, DETN, CLMN DETDEN, CLMEN DETDKO, CLMKO	D ALL D ALLG D IALL D IALLG D DALL D APPS D BIB D BIBG D BIBO D IBIB D IBIBG D BRIEF D BRIEFO D IBRIEF D IBRIEFG D IND D IPC D IPC.TAB D CPC.TAB D MAX D MAXG D MAXO D IMAX D IMAXG D SCAN D STD D ISTD D TRIAL D TX D TXO

DISPLAY and PRINT Formats (cont'd)

Format	Content	Examples
HIT	Hit term(s) and field(s)	D HIT
KWIC	Up to 50 words before and after hit term(s) (KeyWord-In-Context)	D KWIC
OCC	Number of occurrences of hit term(s) and field(s) in which they occur	D OCC

- (1) By default, patent numbers, application and priority numbers are displayed in STN Format. To display them in Derwent format, enter SET PATENT DERWENT at an arrow prompt. To reset display to STN Format, enter SET PATENT STN.
- (2) Custom display only.
- (3) You can combine this display field with the qualifier .PK (Patent Kind Code) to display the content for a certain publication level of a record, e.g., CLM.B2.
- (4) SCAN must be specified on the command line, i.e., D SCAN or DISPLAY SCAN.
- (5) If priority information is not available for a certain document, this information is taken from the application information of this document and marked with an asterisk (*).

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The SELECT command is used to create E-numbers containing terms taken from the specified field in an answer set.

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The SORT command is used to rearrange the search results in either alphabetic or numeric order of the specified field(s).

You can combine all fields except FA with the qualifier .M to SELECT/ANALYZE the content of all publication levels.

Field Name	Field Code	ANALYZE/ SELECT (1)	SORT
Abstract	AB	Y	N
Abstract (English)	ABEN	Y	N
Accession Number	AN	Y	Y
Application Country	AC	Y	Y
Application Date	AD	Y	Y
Application Information	AI (AP)	Y (2)	Y
Application Kind Code	AK	Y (3)	Y
Application Number Group	APPS	Y (2)	Y
Application Number Original	APO	Y	N
Application Year	AY	Y	Y
Cooperative Patent Classification (CPC)	CPC	Y	Y
Entry Date	ED	Y	Y
Data Update Date	DUPD	Y	Y
Document Type	DT (TC)	Y	Y
Entry Date	ED	Y	Y
Entry Date Full-Text	EDTX	Y	Y
Entry Date Patent	EDP	Y	Y
Field Availability	FA	Y	N
International Patent Classification	IC	Y	N
Inventor	IN (AU)	Y	Y
Inventor, Country	IN.CNY	Y	Y
IPC (ICM, ICS, IPCI, IPCR)	IPC	Y	Y
IPC, Advanced Level Symbols	IPC.A	Y (4)	N
IPC, Advanced Level Symbols for Invention	IPC.AI	Y (4)	N
IPC Initial	IPCI	Y	Y
IPC Main	ICM	Y	Y
IPC Reclassified	IPCR	Y	Y
IPC, Reform	IPC.REF	Y	N
IPC Secondary	ICS	Y	Y
Key Terms	KT	Y	N
Language	LA	Y	Y
Language of Filing	LAF	Y	Y
Occurrence Count of Hit Terms	OCC	N	Y

SELECT, ANALYZE, and SORT Fields (cont'd)

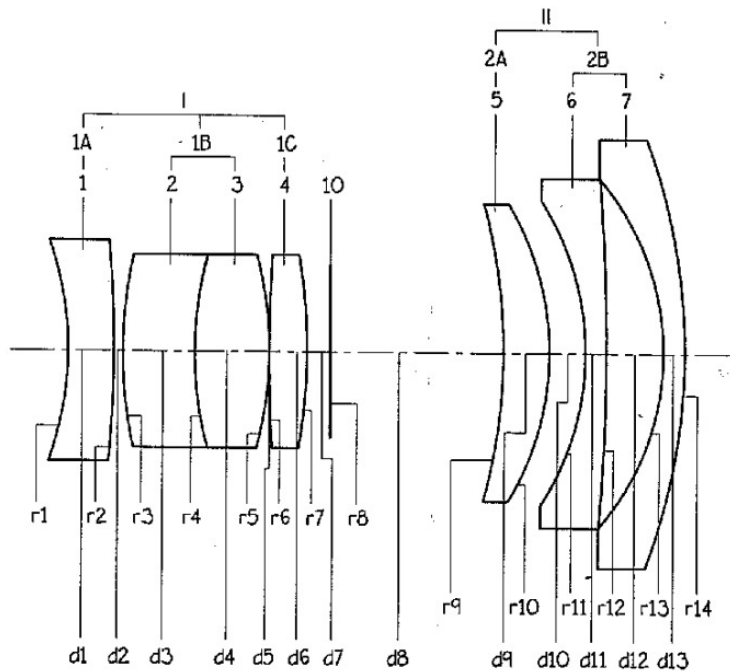
Field Name	Field Code	ANALYZE/ SELECT (1)	SORT
Patent Assignee	PA (CS)	Y	Y
Patent Assignee, Country	PA.CNY	Y	Y
Patent Assignee Normalized	PAN	Y	Y
Patent Assignee Standardized	PAS	Y	Y
Patent Country	PC	Y	Y
Patent Information	PN (PI)	Y (2) (default)	Y
Patent Information Type	PIT	Y	Y
Patent Kind Code	PK	Y	Y
Patent Number Group	PATS	Y (2)	Y
Patent Number Original	PNO	Y	Y
Patent Number/Kind Code	PNK	Y (3)	Y
Patent Status Established Date	STED	Y	Y
Patent Status Indicator	STI	Y	Y
Pre-IPC8 Symbols from the ICM and first IPC8 values from 2006-present	IPC.F	Y (4)	Y
Priority Country	PRC	Y	Y
Priority Date	PRD	Y	Y
Priority Date First	PRDF	Y	Y
Priority Number	PRN (PRAI)	Y (2)	Y
Priority Number Original	PRNO	Y	Y
Priority Year	PRY	Y	Y
Priority Year First	PRYF	Y	Y
Publication Date	PD	Y	Y
Publication Year	PY	Y	Y
Related Application Country	RLC	Y	Y
Related Application Date	RLD	Y	Y
Related Application Number	RLN	Y (2)	Y
Related Application Type	RLT	Y	N
Related Application Year	RLY	Y	Y
Related Patent Country	RLPC	Y	Y
Related Patent Number	RLPN	Y (2)	Y
Related Publication Date	RLPD	Y	Y
Related Publication Year	RLPY	Y	Y
Title	TI	Y	Y
Title (English)	TIEN	Y	Y
Ultimate Owner	UO	Y	Y
Ultimate Owner Standardized	UOS	Y	Y
Update Date	UP	Y	Y
Update Date Full-Text	UPTX	Y	Y

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- (2) Selects or analyzes application numbers with /AP appended to the terms created by SELECT.
- (3) Appends /BI to the terms created by SELECT.
- (4) Appends /IPC to the terms created by SELECT.

Sample Records

DISPLAY BIBG

L4 ANSWER 1 OF 1 KRFULL COPYRIGHT 2025 LNBIS on STN.
AN 887596 KRFULL EDP 20191022 ED 20191022 UP 20210707 EDTX 20191022
DUPD 20210702 Full-text
TIEN WIDE ANGLE ZOOM LENS OF SMALL SIZE
TIKO 소형 광각 줌렌즈
IN KANG, GEON MO
PA SAMSUNG TECHWIN CO., LTD.
PAS SAMSUNG TECHWIN
PAN SAMSUNG
UO SAMSUNG ELECTRONICS CO., LTD.
UOS Samsung
LAF Korean
LA Korean
DT Patent; (Fulltext)
PI KR 189064 B1 19990114
PIT KRB1 PATENT SPECIFICATION
STI DEAD
AI KR 1996-36723 19960830
PRAI KR 1996-36723 19960830
GI



DISPLAY ISTD.M

L5 ANSWER 1 OF 1 KRFULL COPYRIGHT 2025 LNBIS on STN.
ACCESSION NUMBER: 889200 KRFULL
ENTRY DATE PATENT: 20191022 Full-text
ENTRY DATE: 20191022
UPDATE DATE: 20240904
ENTRY DATE (FULLTEXT): 20191022
DATA ENTRY DATE: 20120208
DATA UPDATE DATE: 20240827
TITLE (ENGLISH): Device tool for etching silicon wafer
TITLE (KOREAN): 자동 색온도
조절 장치
PATENT APPLICANT(S): SAMSUNG AEROSPACE IND
PATENT APPL. STANDARD.: SAMSUNG AEROSPACE INDUSTRIES
PATENT APPL. NORMAL.: SAMSUNG
ULTIMATE OWNER: HANWHA AEROSPACE CO LTD
ULTIMATE OWNER STANDARD: Hanwha Aerospace
LANGUAGE OF FILING: Korean
LANGUAGE OF PUBL.: Korean
DOCUMENT TYPE: Patent; (Fulltext)
PATENT INFORMATION: KR 98017371 A 19980605
PATENT INFO. TYPE: KRA OFFICIAL GAZETTE OF THE UNEXAMINED PATENTS
PATENT STATUS INDICATOR: DEAD
APPLICATION INFO.: KR 1996-37147 A 19960830
PRIORITY INFO.: KR 1996-37147 19960830
INT. PATENT CLASSIF.:
MAIN: H04N0009-07
IPC RECLASSIF.: H04N0023-12 [I,A]
CPC CLASSIF.: H04N0023-88

ACCESSION NUMBER: 889200 KRFULL
ENTRY DATE PATENT: 20191022 Full-text
ENTRY DATE: 20191022
UPDATE DATE: 20240904
ENTRY DATE (FULLTEXT): 20191022
DATA UPDATE DATE: 20240827
TITLE (ENGLISH): AUTOMATIC COLOR TEMPERATURE CONTROL DEVICE
TITLE (KOREAN): 자동 색온도
조절 장치
INVENTOR(S): CHO, JAE HAN
PATENT APPLICANT(S): SAMSUNG TECHWIN CO., LTD.
PATENT APPL. STANDARD.: SAMSUNG TECHWIN
PATENT APPL. NORMAL.: SAMSUNG
ULTIMATE OWNER: HANWHA AEROSPACE CO LTD
ULTIMATE OWNER STANDARD: Hanwha Aerospace
LANGUAGE OF FILING: Korean
LANGUAGE OF PUBL.: Korean
DOCUMENT TYPE: Patent; (Fulltext)
PATENT INFORMATION: KR 235456 B1 19990927
PATENT INFO. TYPE: KRB1 PATENT SPECIFICATION
PATENT STATUS INDICATOR: DEAD
APPLICATION INFO.: KR 1996-37147 19960830
PRIORITY INFO.: KR 1996-37147 19960830
INT. PATENT CLASSIF.:
MAIN: H04N0009-07 (6)
IPC RECLASSIF.: H04N0023-12 [I,A]
CPC CLASSIF.: H04N0023-88

DISPLAY BRIEFO

L6 ANSWER 1 OF 1 KRFULL COPYRIGHT 2025 LNBIS on STN.
AN 3744609 KRFULL EDP 20191022 ED 20191022 UP 20250423 EDTX 20191022
DED 20151009 DUPD 20250422 Full-text
TIEN Apparatus for cutting an electrode using laser and electrode supply
method of the same
TIKO 레이저를 이용한
전극 커팅 장치 및 그
전극 공급 방법
IN MIN, KI HONG; AHN, CHANG BUM; YANG, YOUNG JOO
INKO 민기홍, 대전광역시
유성구 문지로 188 LG화학
기술연구원 내, KR
안창범, 대전광역시
유성구 문지로 188 LG화학
기술연구원 내, KR
...
PA LG CHEM. LTD.
PAS LG CHEM
PAN LG
PAKO 주식회사 엘지화학,
서울특별시
영등포구 여의대로 128
(여의도동), KR
UO LG CHEM CO.,LTD.
UOS LG Chem
AGKO 특허법인태평양
LAF Korean
LA Korean
DT Patent; (Fulltext)
PIT KRA OFFICIAL GAZETTE OF THE UNEXAMINED PATENTS
PI KR 2015102771 A 20150908
STI DEAD
AI KR 2013-129785 20131030
PRAI KR 2013-129785 20131030
IPCR B23K0026-10 [I,A]; B23K0026-38 [I,A]; B23K0026-70 [I,A]
CPC B23K0037-04; B23K0026-38; B23K0026-083; B23K0026-142; B23K2101-40
ABEN
Original
An apparatus for cutting an electrode using a laser is disclosed.
According to an embodiment of the present invention, the apparatus for
cutting an electrode using a laser comprises: a laser cutter for
irradiating a laser beam; a transfer gripper which transfers an
electrode sheet to a position to be irradiated with a laser beam and
fixates the electrode sheet during the irradiation of the laser beam;
and a rear gripper which transfers a unit electrode body cut by the
laser beam and fixates the electrode sheet during the irradiation of the
laser beam.
COPYRIGHT KIPO 2015

ABKO
본 실시예는
레이저를 이용한
전극 커팅 장치를
. . .

MCLMEN

[CLM0001]

Laser beam emitting device laser cutter; said electrode sheets the transfer to a position in which the wall irradiation laser beam, said laser beam/drain region are formed said electrode sheets gripper transfer the body has a concave insertion hole; and thus cut off may be gas stream classifier and process said unit electrode are conveyed the, said laser beam/drain region are formed said electrode sheets the holders rear the body has a concave insertion hole including an electrode laser cutting device.

MCLMKO

[CLM0001] !@ 레이저빔을

조사하는 레이저

커터;전극시트를

상기 레이저빔이

. . .

KT

electrode supply method; laser beam; electrode sheet; laser cutter; electrode cutting device; electrode body; transfer gripper; secondary battery electrode assembly; laser electrode; electrode transfer; electrode surface; gas stream classifier; electrode len; negative electrode; laser cutting system; water-electrode sheet; holder modulator; telephone number recording book; low-voltage short failure; energy source; auxiliary power; crank throw roll state; concave insertion hole; modulator cutting system; suction piping; laser power box; suction sputtering; suction pipe connection; wireless secondary battery; modulator cutter

DISPLAY ALL (STN format)

AN 3744609 KRFULL EDP 20191022 ED 20191022 UP 20250423 EDTX 20191022
DED 20151009 DUPD 20250422 Full-text

TIEN Apparatus for cutting an electrode using laser and electrode supply
method of the same

TIKO 레이저를 이용한
전극 커팅 장치 및 그
전극 공급 방법

IN MIN, KI HONG; AHN, CHANG BUM; YANG, YOUNG JOO

PA LG CHEM. LTD.

PAS LG CHEM

PAN LG

UO LG CHEM CO.,LTD.

UOS LG Chem

AGKO 특허법인태평양

LAF Korean

LA Korean

DT Patent; (Fulltext)

PI KR 2015102771 A 20150908

PIT KRA OFFICIAL GAZETTE OF THE UNEXAMINED PATENTS

STI DEAD

AI KR 2013-129785 20131030

PRAI KR 2013-129785 20131030

IPCR B23K0026-10 [I,A]; B23K0026-38 [I,A]; B23K0026-70 [I,A]

CPC B23K0037-04; B23K0026-38; B23K0026-083; B23K0026-142; B23K2101-40

ABEN

Original

An apparatus for cutting an electrode using a laser is disclosed. According to an embodiment of the present invention, the apparatus for cutting an electrode using a laser comprises: a laser cutter for irradiating a laser beam; a transfer gripper which transfers an

electrode sheet to a position to be irradiated with a laser beam and fixates the electrode sheet during the irradiation of the laser beam; and a rear gripper which transfers a unit electrode body cut by the laser beam and fixates the electrode sheet during the irradiation of the laser beam.
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DETDEN

[DESC0001] The present invention refers to cutting electrode is provided to device, more specifically be cut electrode is in a novel manner to prevent the movement of material is to suppress telephone number recording book device, a laser power box and accessible therein electrode is installed is (spatter) to prevent the flow of oil to cutting is an electrode capable of relates to device.

[DESC0002] Recent, wireless secondary battery capable of charging/discharging auxiliary power or energy source in a mobile device device carried out at a wide variety of uses or the like. Furthermore, secondary battery, there is provided a fossil fuel using conventional gasoline vehicle, diesel catalyst-air pollution sending telephone number displayed to the other limit is calculated measures (EV) electric vehicle, hybrid electric vehicle (HEV), plug-in hybrid electric vehicle power source such as at least substantially co-extensive in the spotlight (Plug-In HEV).

[DESC0003] Such secondary battery electrode assembly is electrolyte solution and together in a embedded battery case is produced. The, electrode assembly comprises the anode assembly units with respect to two non isolation and binder which can be to the source portion and the. Medium oil for such electrode assembly supports an anode and a cathode. it is required that a prepared first.

. . .

[DESC0032] 2: electrode sheet 4: unit electrode body 10: laser cutter 20: transfer gripper 20a: upper gripper 20b: lower gripper 22: dust collecting section 24: suction pipe connection 30: rear gripper 30a: upper gripper 30b: lower gripper 32: dust collecting section 34: suction pipe connection

CLMEN

[CLM0001]

Laser beam emitting device laser cutter; said electrode sheets the transfer to a position in which the wall irradiation laser beam, said laser beam/drain region are formed said electrode sheets gripper transfer the body has a concave insertion hole; and thus cut off may be gas stream classifier and process said unit electrode are conveyed the, said laser beam/drain region are formed said electrode sheets the holders rear the body has a concave insertion hole including an electrode laser cutting device.

[CLM0002]

According to Claim 1, said transfer grip it ladles, minute description electrode sheet based on the direction of progress of said laser cutter lies in front of an electrode laser characterized by to cutting device.

[CLM0003]

According to Claim 2, said transfer grip it ladles, minute description electrode sheet partially etched to form a lower surface after pressurization of the number 1 to number 1 lower the holders upper grip pitch correction laser characterized by including an electrode cutting device.

. . .

[CLM0019]

According to Claim 18, lower pitch correction grip upper gripper transfer 300 step said number 4 the holders modulator said therebetween in an oblique-line direction easily and to carry and handle easily the rotating cutter front toward the cast position to a liquid phase silicon compound characterized by including an electrode transfer of device cutting electrode method.

KT

electrode supply method; laser beam; electrode sheet; laser cutter;
electrode cutting device; electrode body; transfer gripper; secondary
battery electrode assembly; laser electrode; electrode transfer;
electrode surface; gas stream classifier; electrode len; negative
electrode; laser cutting system; water-electrode sheet; holder
modulator; telephone number recording book; low-voltage short failure;
energy source; auxiliary power; crank throw roll state; concave
insertion hole; modulator cutting system; suction piping; laser power
box; suction sputtering; suction pipe connection; wireless secondary
battery; modulator cutter

In North America

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Phone: 800-753-4227 (North America)
614-447-3731 (worldwide)
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E-mail: EMEAhelp@cas.org
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customer@jaici.or.jp (Customer Service)
Internet: www.jaici.or.jp